



**Delivering pervasive  
semiconductors for  
humankind**



# Disclaimer

This presentation and the accompanying oral presentation include “forward-looking statements,” that reflect our current expectations and views of future events. These forward-looking statements are made under the “safe harbor” provisions of the U.S. Private Securities Litigation Reform Act of 1995 and include but are not limited to, statements regarding our financial outlook, future guidance, product development, business strategy and plans, and market trends, opportunities and positioning. These statements are based on current expectations, assumptions, estimates, forecasts, projections and limited information available at the time they are made. Words such as “expect,” “anticipate,” “should,” “believe,” “hope,” “target,” “project,” “goals,” “estimate,” “potential,” “predict,” “may,” “will,” “might,” “could,” “intend,” “shall,” “outlook,” “on track,” and variations of these terms or the negative of these terms and similar expressions are intended to identify these forward-looking statements, although not all forward-looking statements contain these identifying words. Forward-looking statements are subject to a broad variety of risks and uncertainties both known and unknown. Any inaccuracy in our assumptions and estimates could affect the realization of the expectations or forecasts in these forward-looking statements. For example, our business could be impacted by the COVID-19 pandemic and supply chain disruptions due to the Russia/Ukraine conflict and actions taken in response to such events; the market for our products may develop more slowly than expected or than it has in the past; our operating results may fluctuate more than expected; there may be significant fluctuations in our results of operations and cash flows related to our revenue recognition or otherwise; a network or data security incident that allows unauthorized access to our network or data or our customers’ data could damage our reputation; we could experience interruptions or performance problems associated with our technology, including a service outage; and global economic conditions could deteriorate. It is not possible for us to predict all risks, nor can we assess the impact of all factors on our business or the extent to which any factor, or combination of factors, may cause actual results or outcomes to differ materially from those contained in any forward-looking statements we may make. Moreover, we operate in a competitive and rapidly changing market, and new risks may emerge from time to time. You should not rely upon forward-looking statements as predictions of future events. These statements are based on our historical performance and on our current plans, estimates and projections in light of information currently available to us, and therefore you should not place undue reliance on them.

Although we believe that the expectations reflected in our statements are reasonable, we cannot guarantee that the future results, levels of activity, performance or events and circumstances described in the forward-looking statements will be achieved or occur. Moreover, neither we, nor any other person, assumes responsibility for the accuracy and completeness of these statements. Recipients are cautioned not to place undue reliance on these forward-looking statements, which speak only as of the date such statements are made and should not be construed as statements of fact. Except to the extent required by federal securities laws, we undertake no obligation to update any information or any forward-looking statements as a result of new information, subsequent events, or any other circumstances after the date hereof, or to reflect the occurrence of unanticipated events.

This presentation and the accompanying oral presentation also contain estimates and other statistical data made by independent parties and by us relating to market size and growth and other data about our industry and business. This data involves a number of assumptions and limitations, and you are cautioned not to give undue weight to such estimates. We have not independently verified the industry data generated by independent parties and contained in this presentation and, accordingly, we cannot guarantee their accuracy or completeness. In addition, projections, assumptions, and estimates of our future performance and the future performance of the markets in which we compete are necessarily subject to a high degree of uncertainty and risk.

In addition to the financial information presented in accordance with International Financial Reporting Standards (“IFRS”), this presentation includes the following adjusted non-IFRS metrics: adjusted gross profit (loss), adjusted gross margin, adjusted net income (loss), adjusted diluted earnings (loss) per share and adjusted EBITDA. We define adjusted gross profit (loss) as gross profit (loss) adjusted for share-based compensation expense. We define adjusted gross margin as adjusted gross profit (loss), which is gross profit (loss) before share-based compensation, divided by net revenues. We define adjusted operating profit (loss) as profit (loss) from operations adjusted for share-based compensation expense. We define adjusted operating margin as adjusted operating profit (loss) divided by net revenues. We define adjusted net income (loss) as net income (loss) adjusted for share-based compensation expense. We define adjusted diluted earnings (loss) per share as adjusted net income (loss) divided by the dilutive shares. We define adjusted EBITDA as net income (loss), excluding the impact of finance expense, income tax expense, depreciation, amortization, share-based compensation expense, transaction gains and associated expenses, restructuring charges and litigation settlements. We define adjusted EBITDA margin as adjusted EBITDA divided by net revenues.

We believe that in addition to our results determined in accordance with IFRS, these adjusted non-IFRS measures provide useful information to both management and investors in measuring our financial performance and highlight trends in our business that may not otherwise be apparent when relying solely on IFRS measures. These adjusted non-IFRS financial measures provide supplemental information regarding our operating performance that excludes certain gains, losses and non-cash charges that occur relatively infrequently and/or that we consider to be unrelated to our core operations. For further information regarding these non-IFRS measures, please refer to “Appendix” in this presentation.

Adjusted non-IFRS financial information is presented for supplemental informational purposes only and should not be considered in isolation or as a substitute for financial information presented in accordance with IFRS. Our presentation of adjusted non-IFRS measures should not be construed as an inference that our future results will be unaffected by unusual or nonrecurring items. Other companies in our industry may calculate these measures differently, which may limit their usefulness as a comparative measure.





**Delivering a  
new era of more**



 **more**  
 **innovation**



 **more**  
 **impact**



# GF at a glance

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**\$6.6B**

2021 revenue

**2.4M**

2021 wafer shipments  
(300mm eq.)

**>200**

customers in 2021

**5**

manufacturing sites  
across three continents

**~15,000**

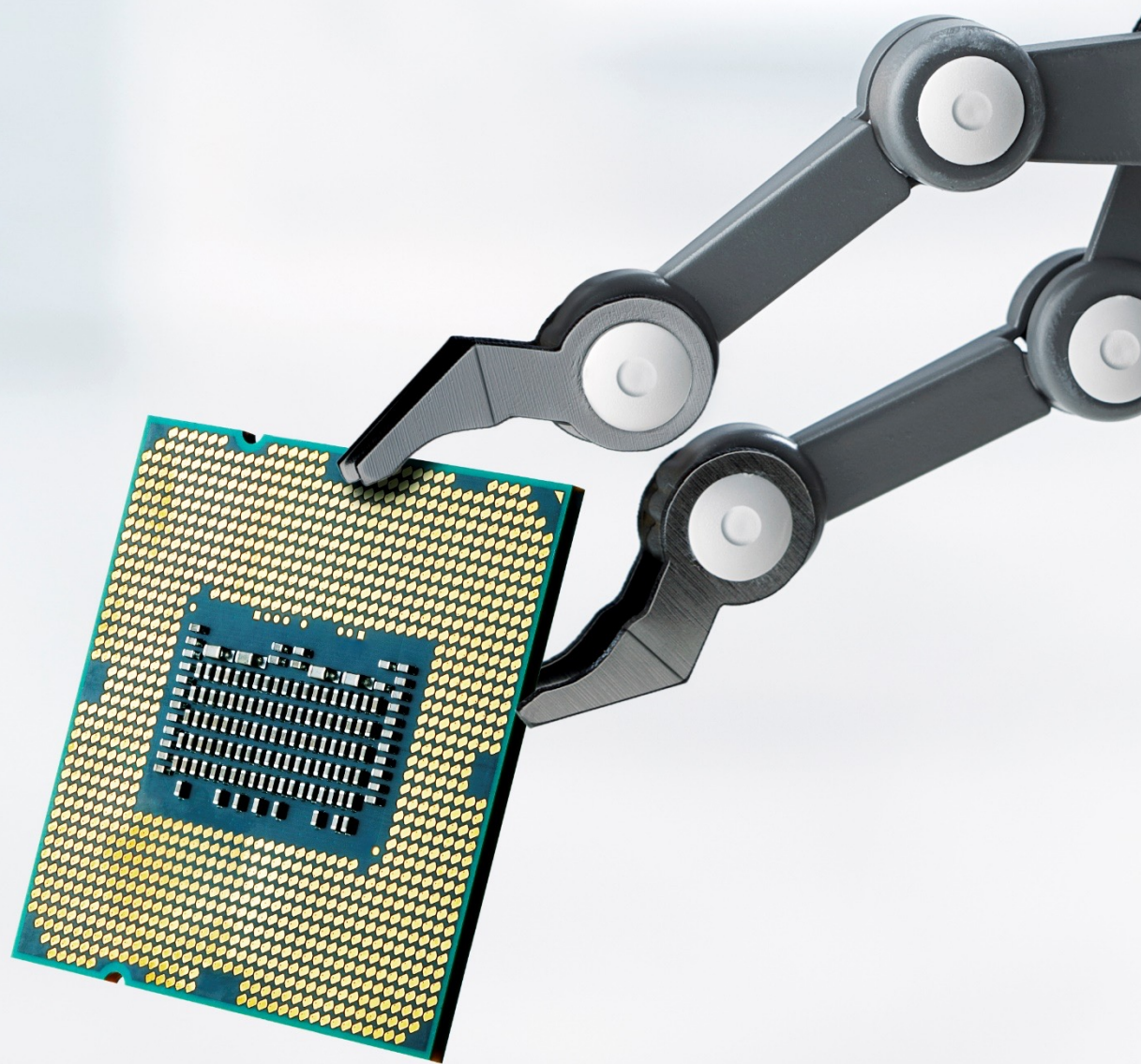
employees

**~10,000**

patents

**10.28.21**

GFS Nasdaq listed





# GF journey

## Creation

GlobalFoundries was created based on the thesis that the world needed a geographically diverse alternative to Taiwan



2009

2017

2018

## Transformation

Strategically re-positioned to serve pervasive semiconductor end markets

- Strengthened management team aligned to mission
- Refocused investments & accelerated differentiated solutions focused on pervasive markets
- Increased single-sourced products
- Driving margin expansion and earnings growth



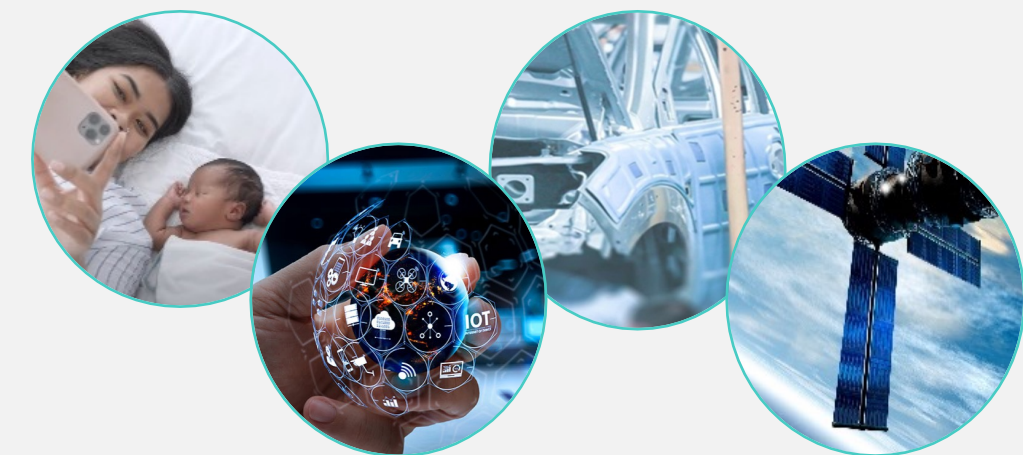
2021

2022

## Realization

The world's leading manufacturer of feature-rich semiconductor solutions

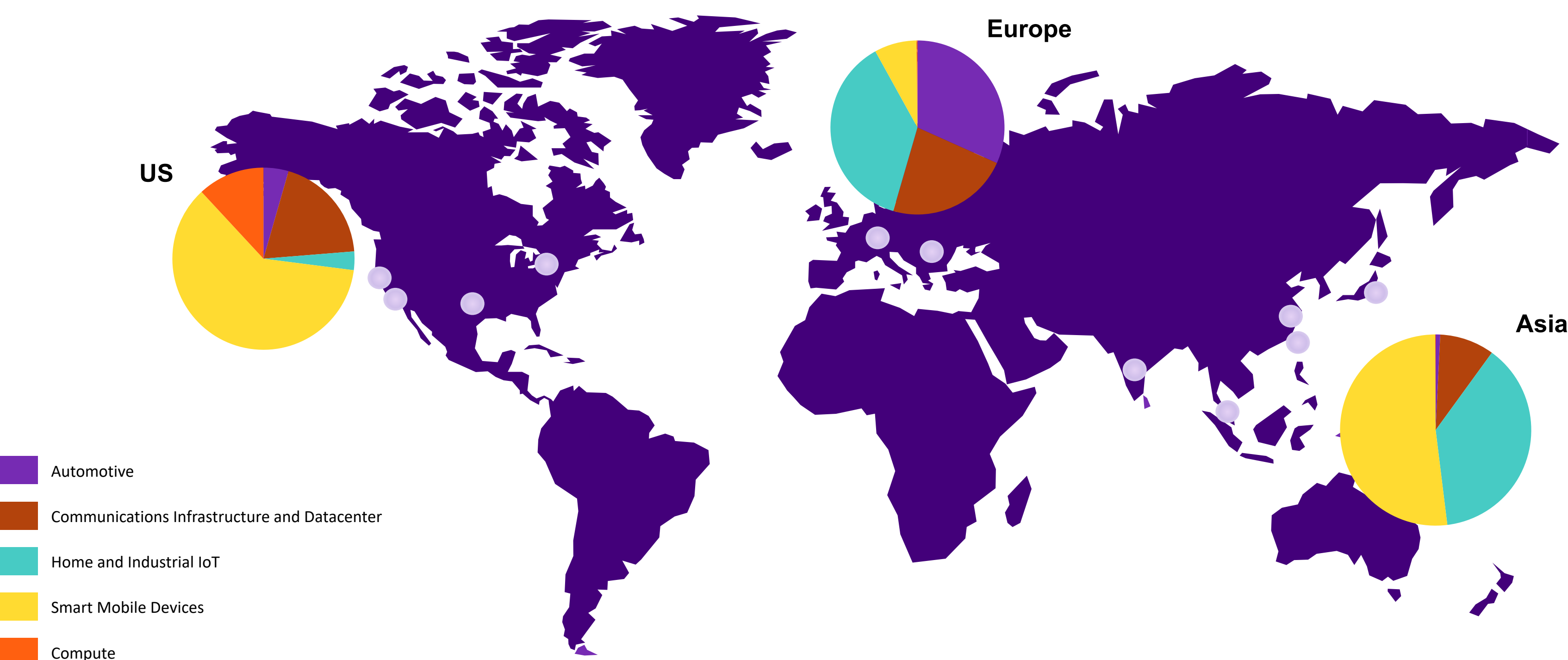
- Gain share in secular end-markets
- Innovate in purpose-built platforms and solutions
- Capital efficient expansion through partnerships
- Deliver best-in-class financials



2030



# Delivering solutions to customers around the globe



- Automotive
- Communications Infrastructure and Datacenter
- Home and Industrial IoT
- Smart Mobile Devices
- Compute
- GF Field Site



**10**  
Countries  
and time zones

**11**  
Service  
languages

**<10 km**  
Median proximity  
to top customers



# Purpose-built customer engagements

## Certainty

**~80%**

2022-2025 capacity covered by LTAs

## Durability

**90%**

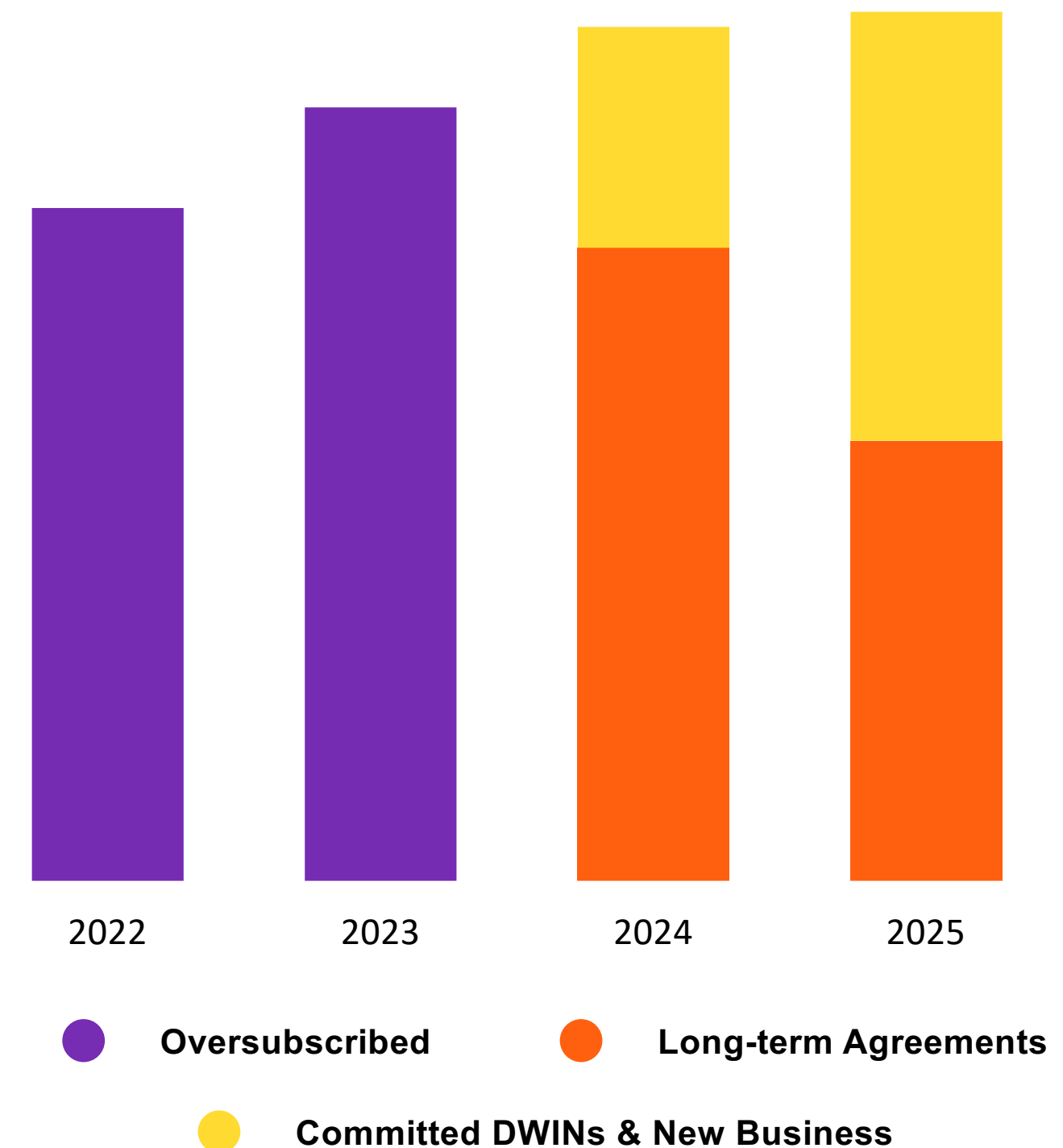
single-sourced DWINs<sup>(1)</sup> in 1H'22

## Profitability

**↑19%**

YoY mix and pricing increase 1H'21 - 1H'22<sup>(2)</sup>

## Multi-year Capacity Coverage



























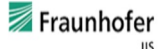
















































### Note:

1. A DWIN, or design win, is defined as the successful completion of the evaluation stage, where a customer has assessed our technology solution, verified that it meets its requirements, qualified it for their products and confirmed to us their selection.
2. Wafer hardware only




# GF's ecosystem: more than a decade in the making


Design enablement network

IP	FDX™	RF	EDA	Design services	OSAT			
        	        	        	        	         	        	          	      	 


Our partner community




**100+**  
*Ecosystem partners spanning IP, EDA, OSAT and design services*




**4500+**  
*Total IP titles across all nodes from >50 IP partners*



**950+**  
*IP titles currently in active development across 26 process nodes and 34 IP partners*



**300+**  
*Clients enabled by ecosystem partner IPs in the last 5 years*



**1700+**  
*Client designs enabled by ecosystem partners in the last 5 years*





# **End-markets and Solutions**



# Technology megatrends shaping the global economy

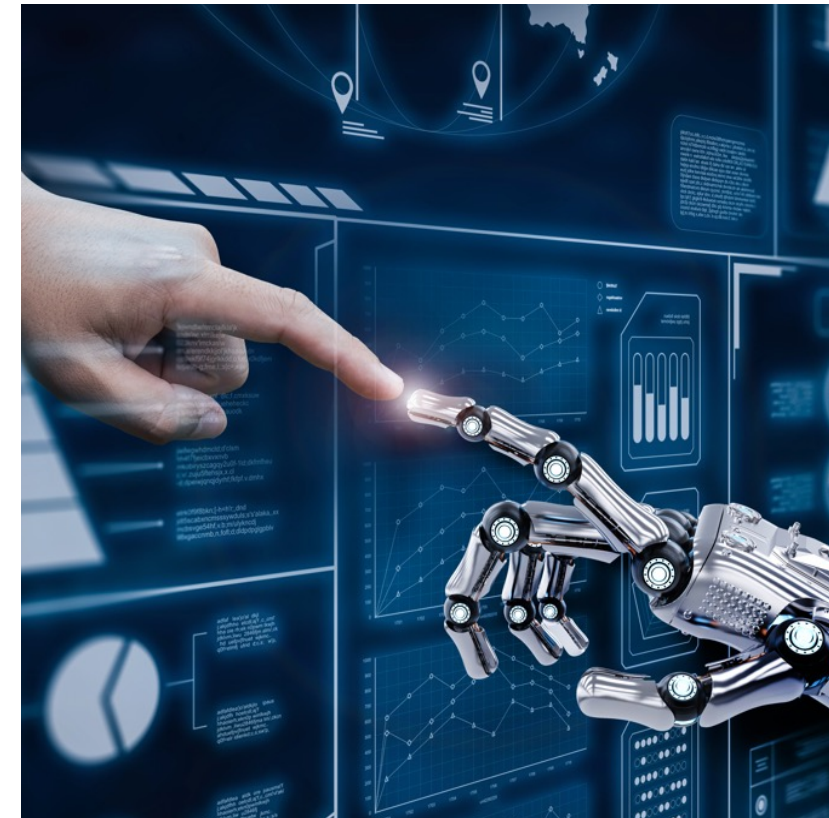
**Smart, connected devices**



**Adoption of AR & VR**



**Explosion of AI & ML**



**Data everywhere**

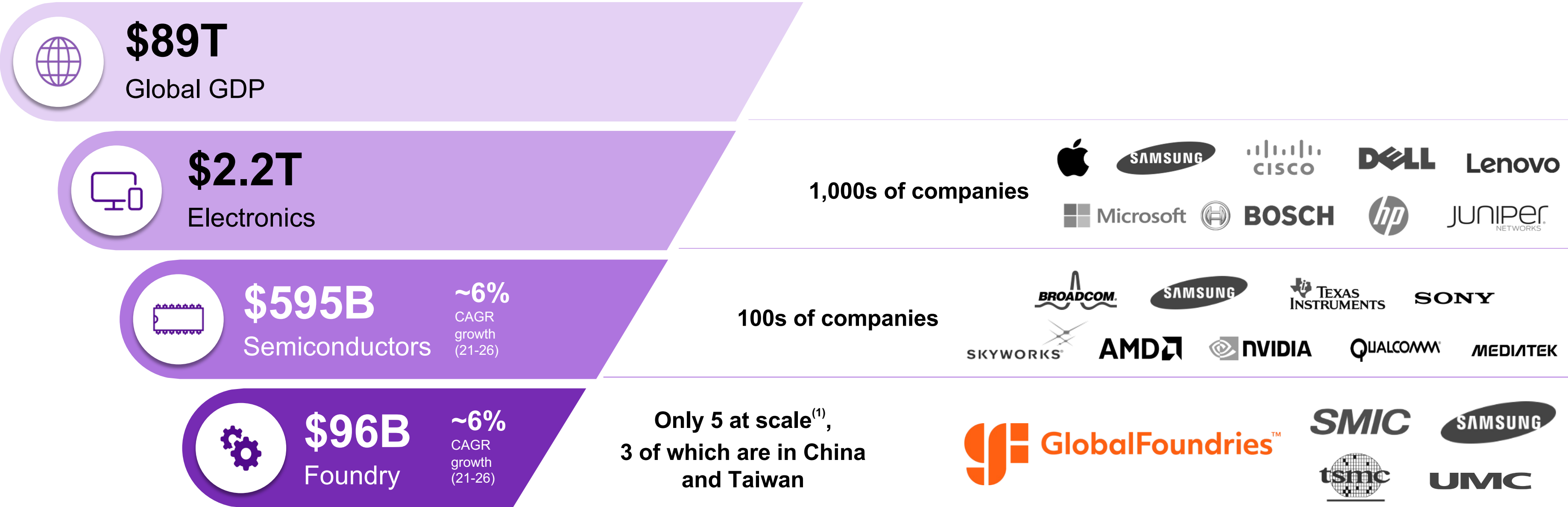


**Megatrends accelerated or limited by semiconductors**



# Foundries are essential to global GDP

Market Size (2021)



Semiconductors outpace GDP & foundry outpaces semiconductors

Source: Global GDP: World Bank, IMF. Electronics; Semiconductors and Foundry: Gartner "Forecast, Semiconductor Foundry Revenue, Supply and Demand, Worldwide, 1Q22 Update (April 2022)

Note:  
1. Excludes smaller foundry players, defined as those with less than \$2Bn of foundry revenue



# Uniquely positioned in markets that matter



**Smart Mobile Devices**



**Home and Industrial IoT**



**Automotive**



**Communications Infrastructure & Datacenter**



# Smart Mobile Devices

## **4G LTE/5G: RF FE Sub-6GHz**

RF SOI

Higher Data Rate  
Power Efficiency

## **5G: RF FE mmWave**

FDX™

Expanded Range  
Power Efficiency

## **4G LTE/5G: Transceiver**

FinFET

Higher Data Rate  
Power Efficiency

## **Wi-Fi: Wi-Fi 6/6E**

FinFET

Higher Data Rate  
Power Efficiency



## **Camera: Optical Imaging**

Feature-Rich CMOS

Sensor Fusion  
Power Efficiency

## **Smart Audio**

Feature-Rich CMOS (BCD, eNVM)

Audio Quality  
Haptic Response

## **Secure Payment: NFC**

Feature-Rich CMOS (eNVM)

Integration of NFC+ Secure Element  
Secure Manufacturing

## **Touch Screen: Display**

Feature-Rich CMOS

Functional Integration  
Power Efficiency

## **Power Management: RF, Audio**

Feature-Rich CMOS (BCDLite®), FDX™

Increased Efficiency  
Smaller Form Factor

**GF has 75% of silicon area in  
top premier smartphones in RF  
FE, Audio & NFC**



# Home and Industrial IoT

## Smart Camera: Image Sensing

FDX™

Edge Intelligence  
Low Power Connectivity

## Smart Features: SoC

Feature-Rich CMOS

High Transfer Rate  
Power Efficiency  
Edge Intelligence

## Smart Control: WL MCU

FDX™

Power  
Wireless (BLE, Wi-Fi, 15.4)

## Smart Features: MCU

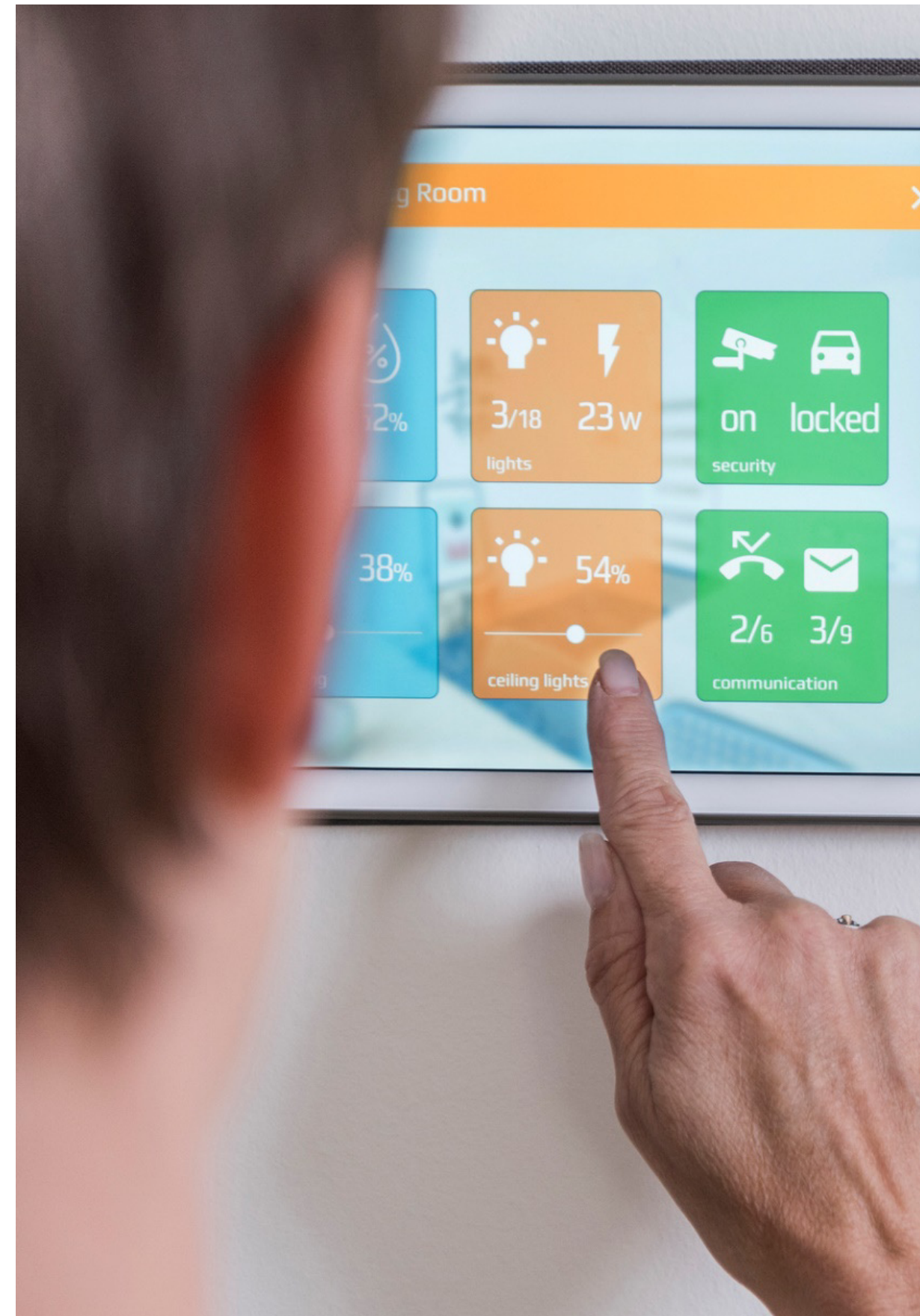
Feature-Rich CMOS (BCD)

Power Management

## Secure Transactions/ Interactions: NFC

Feature-Rich CMOS (eNVM)

Power Efficiency



## Smart Speaker: Audio

Feature-Rich CMOS (BCD, eNVM)

Power Efficiency  
Power Management

## Wi-Fi Connection: Wi-Fi

FDX™

Edge Intelligence  
Low Power Connectivity

## Touch Screen: Display

Feature-Rich CMOS

Sensor Fusion  
Power Efficiency

## Medical IoT: Medical Sensing

FDX™

Edge Intelligence  
Low Power Connectivity



# Automotive

## **5G Connection: RF FEM mmWave**

FDX™

RF mmWave  
Low Power Connectivity

## **Vehicle Power: DC-DC, BMS, Charger**

Feature-Rich CMOS (BCD, eNVM)

High Voltage  
Precision  
Power Efficiency  
Power Management

## **Vehicle Network: Zone/Domain/Fusion**

### **Controllers**

FDX™, FinFET

Power Efficiency  
High Performance  
High Temperature

## **Comfort/Customization/**

## **Keyless Entry: MCU, NFC, BLE, UWB**

Feature-Rich CMOS (eNVM)

Power Efficiency  
Edge Intelligence



## **ADAS: Radar**

FDX™

RF mmWave  
Power Efficiency  
Edge Intelligence

## **Touch Screen: Display**

Feature-Rich CMOS

Sensor Fusion  
Power Efficiency

## **ADAS: LiDAR**

Silicon Photonics

High Transfer Rate  
Power Efficiency  
Edge Intelligence

## **User Experience: IVI, Cluster**

Feature-Rich CMOS (BCD)

Power Efficiency  
Power Management



# Communications Infrastructure & Datacenter

## **5G Infrastructure: RF FEM mmWave**

RF SOI, SiGe, 22FDX®

RF mmWave  
Power efficiency

## **5G Infrastructure: Network processor / Switch**

FinFET, Feature-Rich CMOS  
Performance analog/mixed signal

## **Data communications: Redriver**

SiGe  
Signal loss compensation  
Data reliability & integrity

## **4G LTE/5G Infrastructure: RF FEM Sub-6GHz**

RF SOI, SiGe  
RF features  
Power efficiency



## **Connectivity: Optical networking**

Silicon Photonics

Data throughput >4x Cu  
Cu replacement for inter and intra DC  
connectivity

## **Chiplets/2.5D/3D: IOD**

FinFET

Performance analog/mixed signal

## **Novel compute: AI/Photonics/Quantum**

FinFET, Silicon Photonics

System integration: electronics & photonics  
Highest performance/power efficiency

## **Power delivery**

Feature-rich CMOS (BCDLite®)

High Voltage  
High efficiency





**GF is everywhere**





**Global**



**Footprint**



# Manufacturing at a glance



**99%**

line yield up  
to 15 years reliability

**>31M**

hours worked in 2020 at better  
than safety benchmarks

**5**

manufacturing sites  
across three continents

**800 NPIS**

per year, ramped in 6-  
9 months to HVM

**99%**

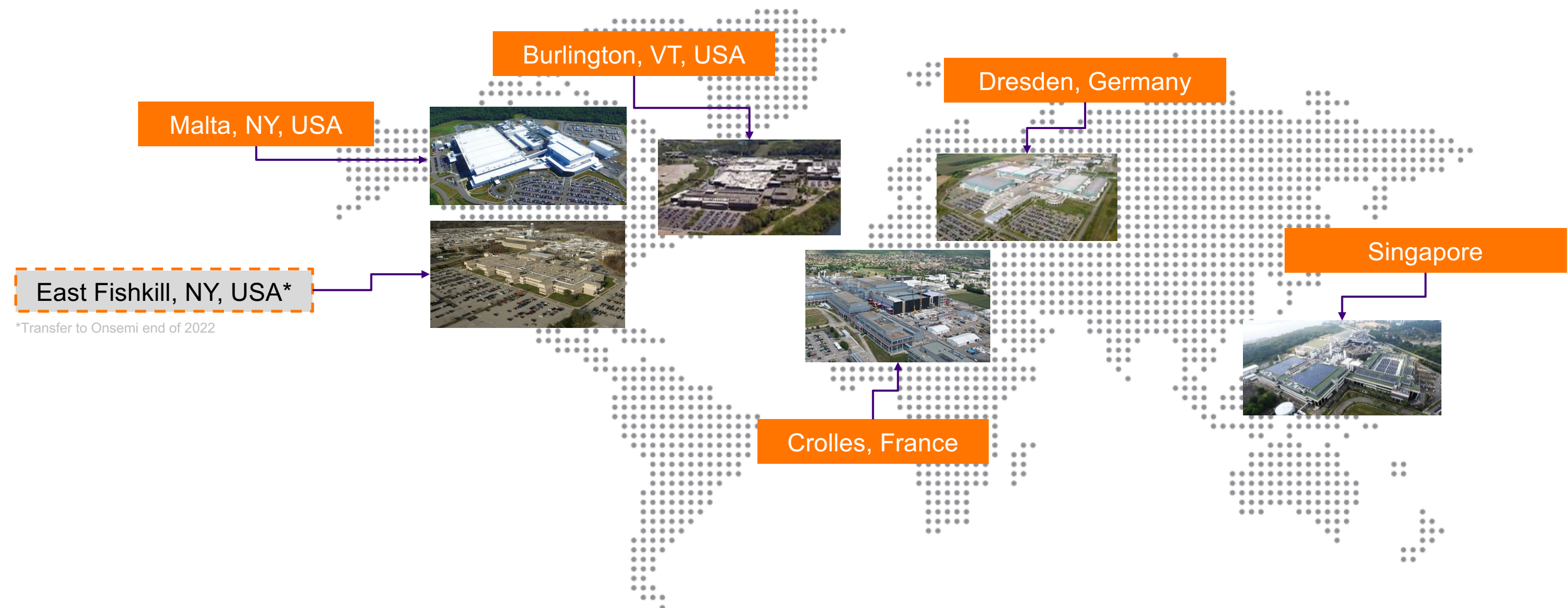
on time delivery

**Zero**

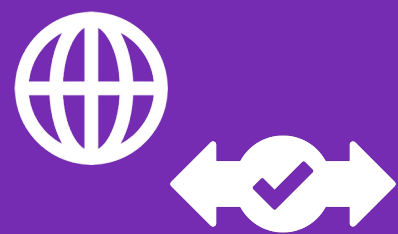
stock outs impacting customer  
commitments



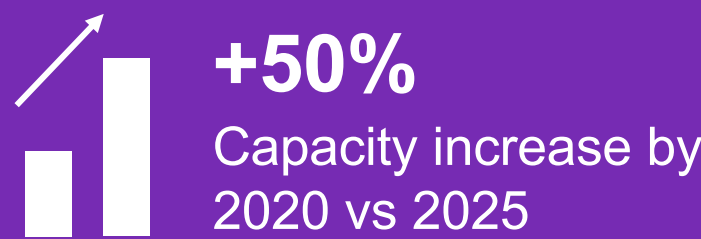
# Global manufacturing footprint & strategy



Supply chain security through  
dual-technology qualification



Economies of scale through  
modular expansion at  
existing sites



Capital efficiency through  
partnership model





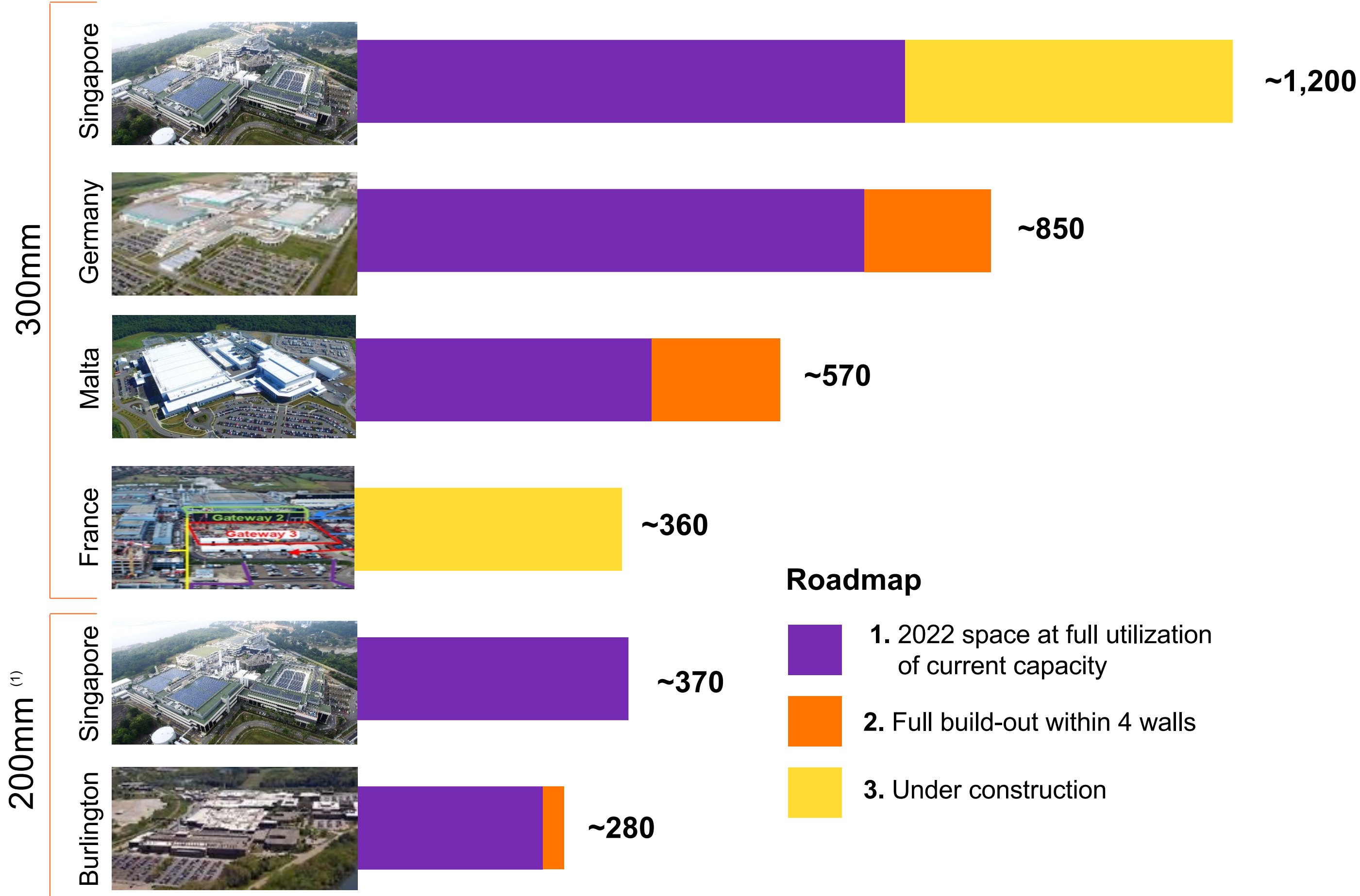
# Global manufacturing footprint - current



**Note:**  
1. Kwpa is defined as 2022 capacity in thousand wafers per annum  
2. 200mm capacity translated to 300mm equivalent



# Capacity expansion roadmap



**Global manufacturing FOOTPRINT** focused on supply security, diversity & sustainability

>50% capacity expansion from 2020 levels

Economy of scale through modular expansion at existing sites in global footprint

Dual site sourcing provides flexibility & security

25% GHG reduction in emissions by 2030

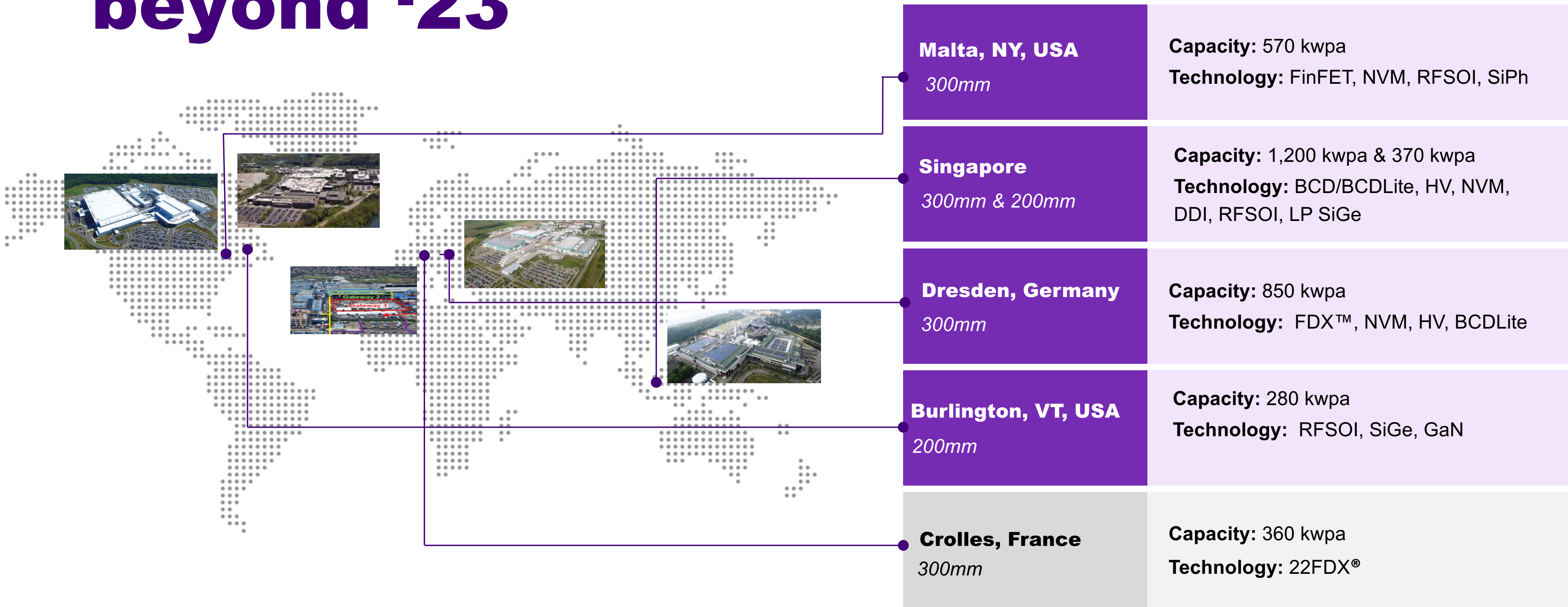
## Roadmap

- 1. 2022 space at full utilization of current capacity
- 2. Full build-out within 4 walls
- 3. Under construction

**Notes:**  
 1. 200mm capacity translated to 300mm equivalent, in kwpa.    2. Full build up Plan through 2028.    3. Does not include future capacity plans under development



# Global manufacturing footprint – beyond ‘23



**Note:**  
1. Kwpa is defined as 2022 capacity in thousand wafers per annum  
2. 200mm capacity translated to 300mm equivalent





# Crolles, France partnership with STMicroelectronics

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## GF co-managed facility

- On site GF management supplemented by Dresden expertise
- Direct oversight of all planning and operations
- Depreciation, fixed and variable cost sharing model based on actual utilization and consumption
- Stable and low-cost energy supply through French Nuclear energy network

**Phase 0:** Install 20 unique FDX™ tools to form pilot line for technology transfer starting 2023

**Phase 1-3:** Ramp starts Q4'24. Full build up to 360kwpa



# Singapore modular expansion

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**First tool-in announced in June 2022**

**Ready for production in 2023**

**>1.5M of 300mm equivalent wafers  
serving Auto, Mobile and IoT**

**Secured government grants and  
customer commitments**







# Malta, NY expansion

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**Expansion announced in July 2021**

**Planning and preliminary  
permitting underway**

**Strong government and  
customer partnerships**

**CHIPS and Science Act signed into  
law in August 2022**



# Sustainable operations

**100%**  
of **3TG** minerals we  
use are conflict free

## 2015-2021



**38%**

Reduction in electricity use intensity



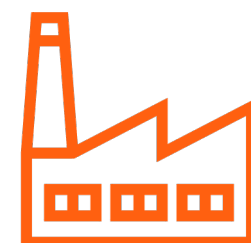
**36%**

Reduction in GHG emissions intensity



**40%**

Reduction in water use intensity



**62,100**

Tons annualized reduction  
of chemical use and waste

## 2022 and Beyond

**33%**

Reduction in electricity use intensity by 2025

**25%**

Absolute reduction in GHG emissions by 2030 <sup>(1)</sup>

**33%**

Reduction in water use intensity by 2025

**90%**

Landfill avoidance in 2022

Journey to  
**ZERO**  
Carbon

**Note:**

1. GHG emissions include scope 1 and 2





**Technology**



**Development**



# Technology Development at a glance



**~1400**

technologists in dedicated research teams

**>30K**

wafers per year dedicated to development

**>50**

universities, government partners and other research institutes partnered in collaborative efforts

**>150**

differentiated programs built on 25+ world class platforms

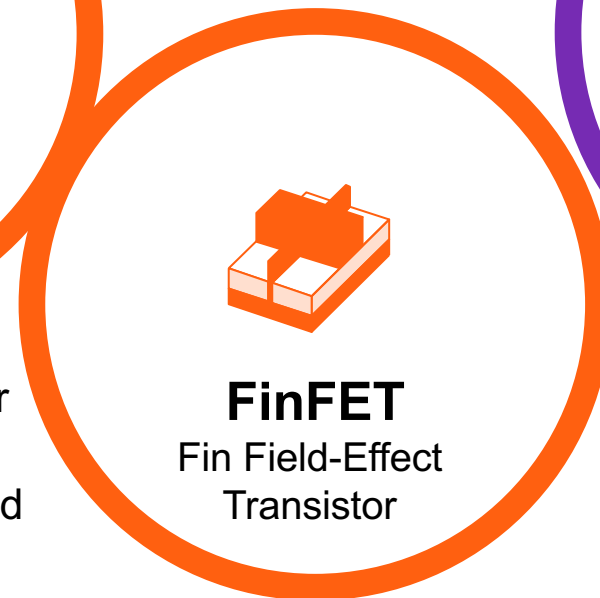


# Innovation through market-driven purpose-built platforms

## Optimizing digital processing & application specific features

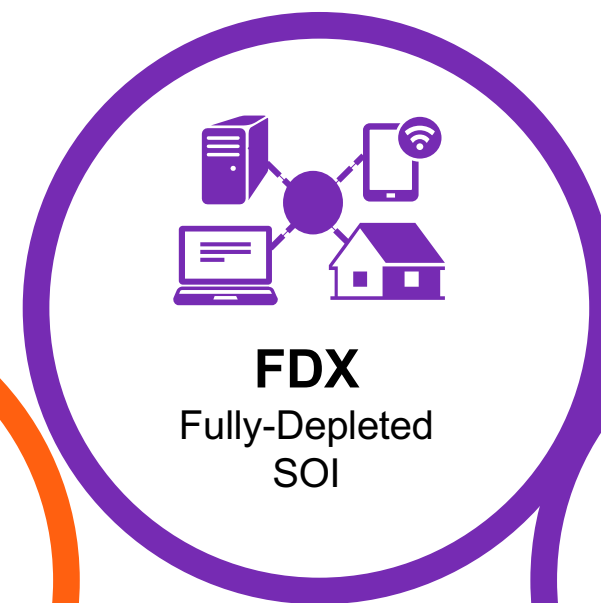


Mixed-technologies for power management, high-voltage, embedded memory

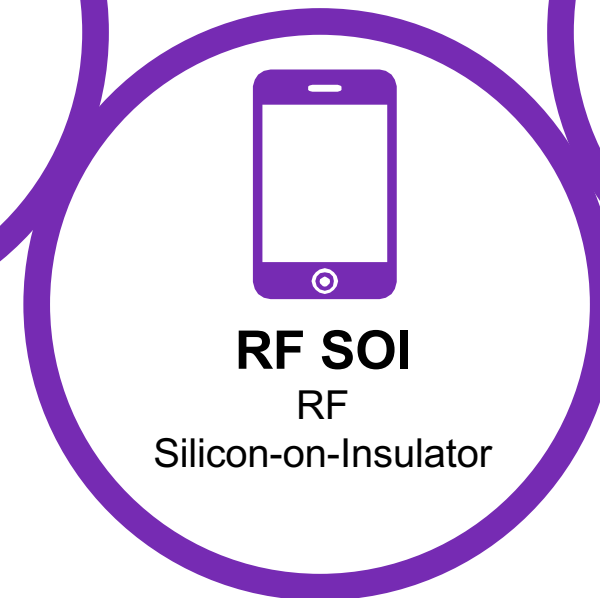


High performance, power efficient "Systems-On-a-Chip"

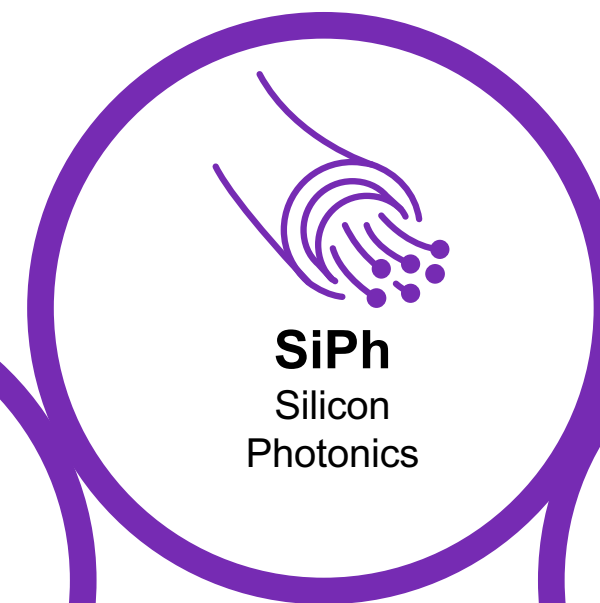
## The ultimate in low power, performance with superior connectivity



Enabling new high-performance, low-power applications



Low power / low noise / low latency / high frequencies



Higher data rates with greater power efficiency



Power amplifier and very-high-frequency applications

## Innovating beyond silicon



High efficiency power conversion

**Innovation beyond transistor size**



# How we innovate: Smart Mobile Device

Ultra-fast, seamless, reliable connectivity

## End user applications



Bridging the cellular and wireless experience effortlessly

## Capabilities required



Rate



Range



Power

## GF's differentiated performance

**RF SOI**

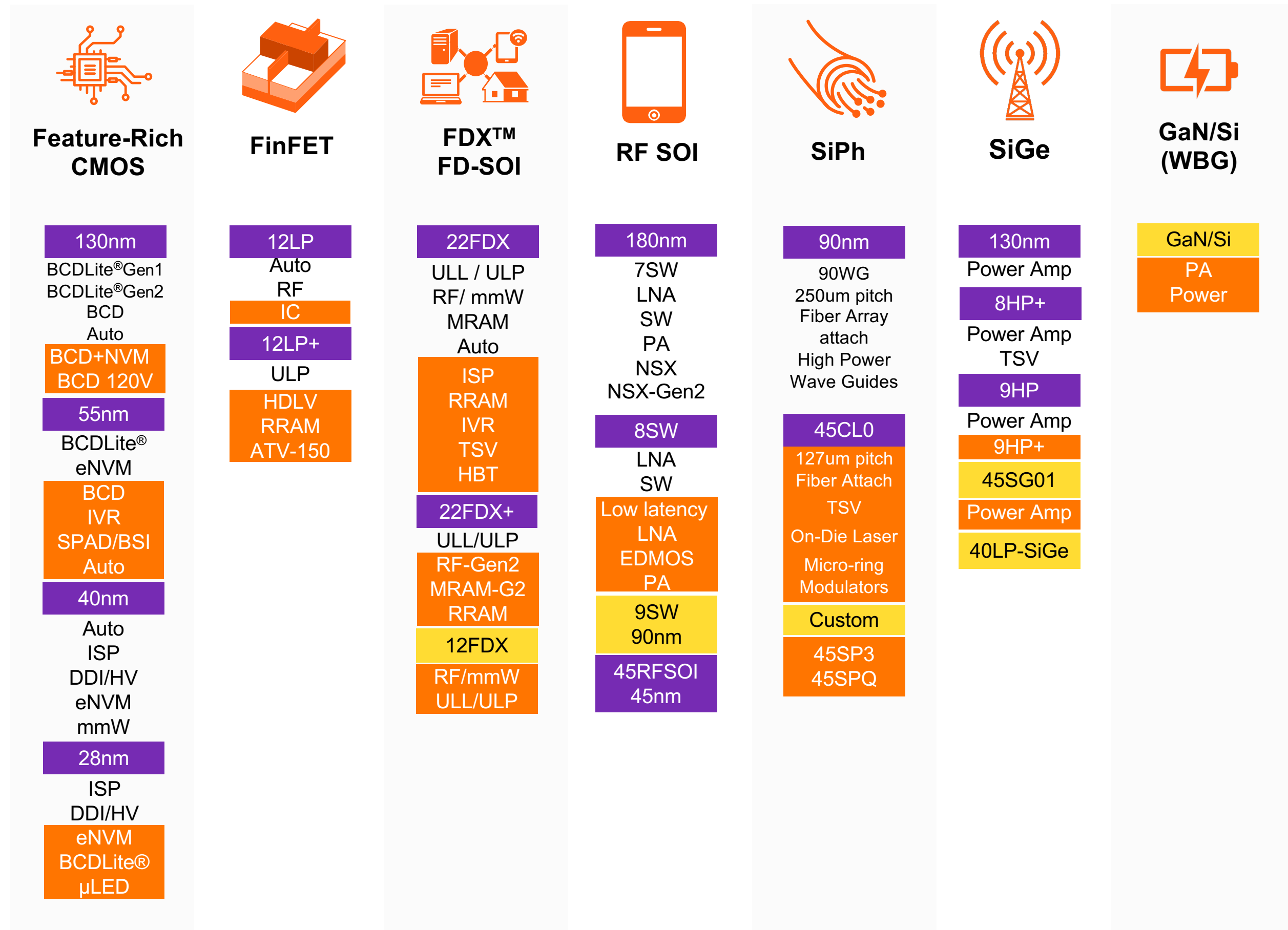
**FDX<sup>TM</sup>**

**SiGe**

**GaN**



# Investing for a bold future



## Huge features portfolio:

120 technology solutions enabling thousands of customer products

## 2022 expansion:

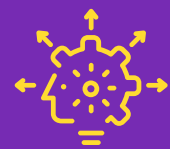
+16 technology solutions  
+ 6 new platforms  
+ dozens of new features in dev.

## Beyond Si solutions:

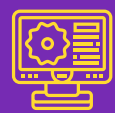
Adding wide bandgap materials for power and RF – GaN/Si



## Physical sciences innovation



Materials enabling new capabilities



New devices to extend and expand applications

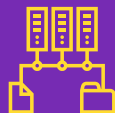


Advanced tooling and processes

## Design innovation



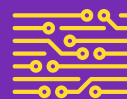
System level architecture explorations



Heterogeneous integration



AI-enabled design



Circuit topologies



## Partnership / ecosystem



Expanded university engagements



Customer collaborative projects



Government supported and targeted R&D



Lab-to-lab

## Market Focus



6G and beyond



AR / VR



Datacenter



Quantum computing



Automotive

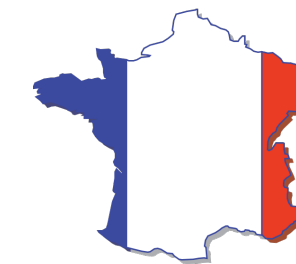


# GF Labs: Our R&D ecosystem of partners

## University Partnerships



## Government Partnerships



## Consortia / R&D Institutes







**Environmental,**



**Social Governance**



# Commitment to ESG



## Environmental

**Journey to Zero Carbon:** 25% Greenhouse Gas (GHG) emissions reduction by 2030

**>36K** annualized metric tons of Carbon equivalent savings achieved in 2019 / 2020

**>415K** annualized cubic meters water savings achieved in 2019 / 2020

## Social

**13** total GF Awards in 2019, 2020 and 2021 for exceptional performance in CSR and EHS

**200 / 200:** Perfect scores in 2020-2021 Responsible Business Alliance audits

**World Class:** GF TRIR 2020 safety rate (0.13) lowest in our history

GF named one of “**America’s Safest Companies**” in 2020\*

## Governance

**4** independent Board directors

**Independent** audit, risk, and compliance committee

**Experienced** global compliance function

Enterprise **risk management framework**

**Conflict-free** supply chain for 3TG: gold, tantalum, tungsten and tin

# GFShield: a foundation of trust



## **Beneficial geopolitical landscape**

During times of increasing international trade conflicts, GF benefits from the resilience of global scale of operations in stable low-risk geographies (United States, Germany and Singapore)

## **Pedigree of secure at-scale manufacturing**

1. Only pure-play foundry in The United States Department of Defense Trusted Foundry Program
2. ISO 15408 Certification to manufacture Common Criteria Secure Products
3. ISO 27001 Certification for Information Security Management

## **Intellectual Property (IP) protection**

With an industry-leading track record protecting GF IP and customers' IP

**In a world of escalating threats and risks in the technology sector,  
our foundation of trust offers a strong competitive edge**



# Supply chain responsibility, resiliency and security



**Trusted Supplier  
to DoD**

Critical Supplier - Defense  
Production Act

**100%**

of **3TG** minerals we  
use are conflict free



**Responsible Business Alliance**

Advancing Sustainability Globally

*“ Completed the RBA validated audit  
process achieving PLATINUM status with a  
full audit score of 200/200 ”*

RBA Recognition, Feb 9

**Stable and Diverse Geographic Footprint**



# **Our Team and Culture**



# Our global team



**~15,000**  
employees

**>90**  
nationalities in  
13 countries

**>1000**  
new college graduates hired  
2018 – present

**~25%**  
female workforce

**~10,500**  
employees working in  
STEM fields

**~75%**  
employees with university  
degrees (PhD, masters,  
bachelors)

**~80%**  
engineers, technicians  
and operators

# GF senior leadership team



**Dr. Thomas Caulfield**  
CEO & President



**David Reeder**  
Chief Financial Officer



**Juan Cordovez**  
Chief Commercial Officer



**Mike Hogan**  
Chief Business Officer



**Gregg Bartlett**  
Chief Technology Officer



**KC Ang**  
Chief Manufacturing Officer



**Mike Cadigan**  
Chief Quality Officer



**Kevin Soukup**  
Chief Strategy Officer



**Pradheepa Raman**  
Chief People Officer



**Laurie Kelly**  
Chief Communications Officer



**Saam Azar**  
General Counsel



# GF board of directors



**Ahmed Yahia Al Idrissi**  
Chairman of the Board



**Dr. Thomas Caulfield**



**Tim Breen**



**Ahmed Saeed Al Calily**



**Glenda Dorchak**  
*Independent*



**Martin L. Edelman**



**David Kerko**  
*Independent*



**Jack Lazar**  
*Independent*



**Elissa Murphy**  
*Independent*



**Carlos Obeid**



**Bobby Yerramilli-Rao**  
*Independent*



# Investing in our team and communities

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**1.4M**

hours invested in training our employees in 2020

**>4300**

GlobalGives employee members

**\$1.2M**

donated in 2021, includes employee donations with corporate funding

**>2500**

Employee resource group members worldwide

- GlobalWomen
- BRAG (Black Resource Affinity Group)
- GlobalFamilies
- VRG (Veterans Resource Group)
- Early Career and Tenure Resource Group
- Unidos, Hispanic/Latinx Resource Group
- ASIA (Asian Society for Inclusion and Awareness), AAPI Resource Group
- Pride@GF, LGBTQ+ Resource Group





## Our Mission

We innovate and partner with our customers to deliver technology solutions for humanity.

We manufacture semiconductors around the globe.



## Our Vision

We are changing the industry that is changing the world.



# Our Values



## Create

- Innovate beyond what is possible today
- Differentiate our technology to enable customer success
- Have a passion for problem-solving
- Create value for our customers and for our shareholders



## Embrace

- Diversity is a competitive advantage
- The best ideas come from being inclusive
- Act with a shared sense of purpose
- Respect everyone



## Partner

- Collaborate across all borders & boundaries
- Strive for win-win outcomes
- Build trust as the basis of every relationship



## Deliver

- Our customers can count on us to deliver on our commitment
- Work effectively, efficiently and decisively
- Focus on outcomes and are accountable for results
- Celebrate and reward success
- Nothing matters without safety

**All with unyielding integrity**



# Links

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[GF.com](#)

[News & Events](#)

[GF Investor Relations Website](#)

[GF Leadership Team](#)

[GF Board of Directors](#)

[Diversity & Inclusion](#)

[Environmental Social Governance at GF](#)

[Careers at GF](#)







# Connect with GF

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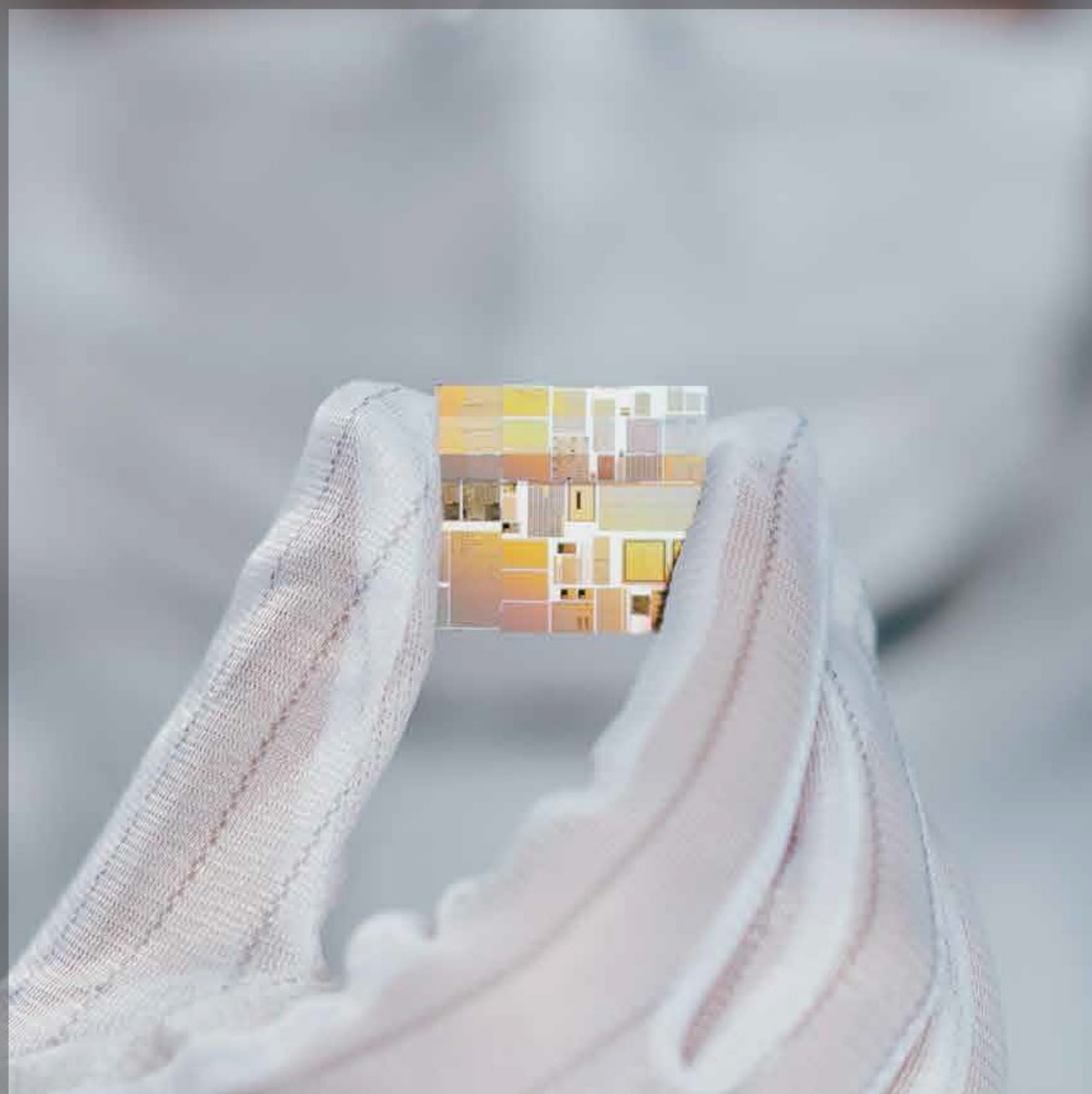


GlobalFoundries



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# Thank You

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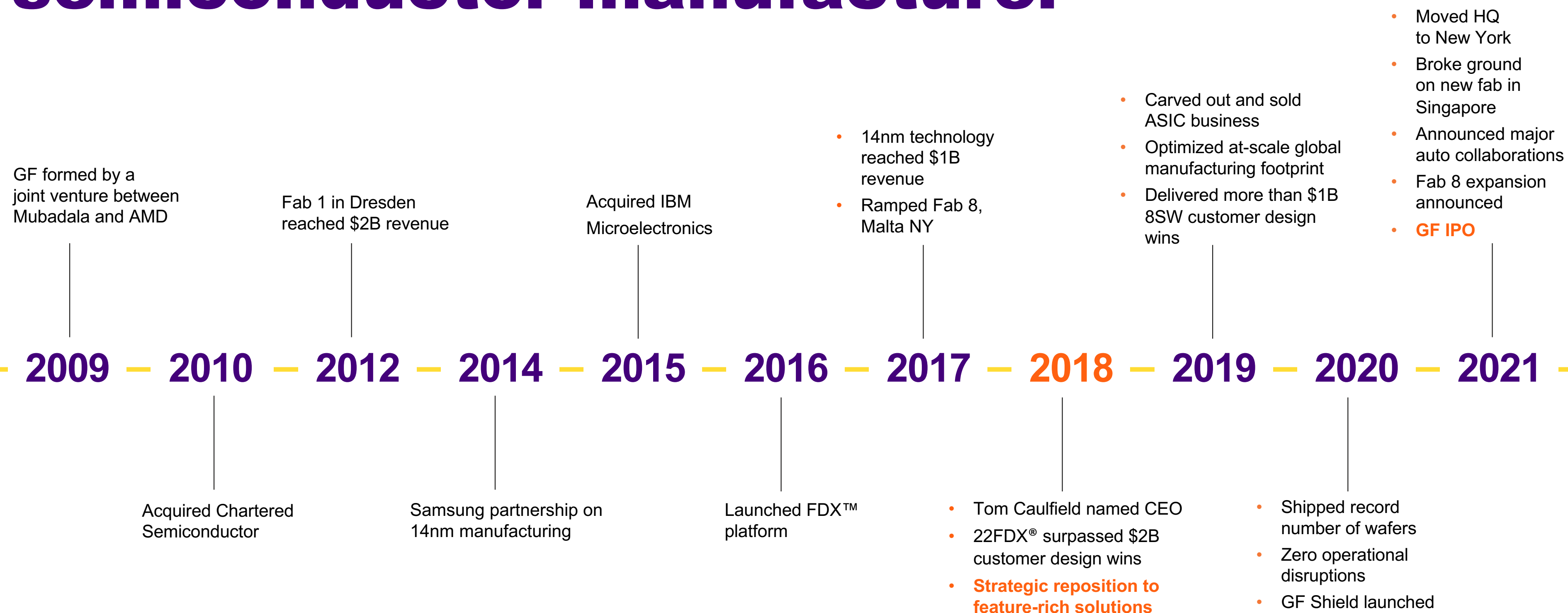
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# Appendix



# The making of a global semiconductor manufacturer





# How we innovate: Industrial & Home IoT

## End user applications



Smart home appliances

Smart speaker

Security system

## Capabilities required



Intuitive



Pain-free



Efficient



Convenient



Trusted

## GF's differentiated performance

**FDX<sup>®</sup>**

**Feature rich  
CMOS**

**BCD**

**NVM**

# How we innovate: next gen 5G infrastructure

## End user applications



Increased range + greater area coverage

Increased data rate + low latency for HD video and AR/VR

## Capabilities required



5G sub 8GHz / mmWave



Satellite Communications



Reliability / availability

## GF's differentiated performance

**SiGe**

**Feature-rich CMOS**

**FDX<sup>®</sup>**



# How we innovate: Smart Mobile Device

## End user applications



Hyperconnected human experience bridging physical & digital worlds

## Capabilities required



Touch



Hear



See



Trust

## GF's differentiated performance

**FDX<sup>®</sup>**

**BCDL<sup>®</sup>**

**NVM**

**HV**

# How we innovate: Industrial & Home IoT

## End user applications



Video streaming  
Connected camera  
Smart home

## Capabilities required



Rate



Range



Battery life

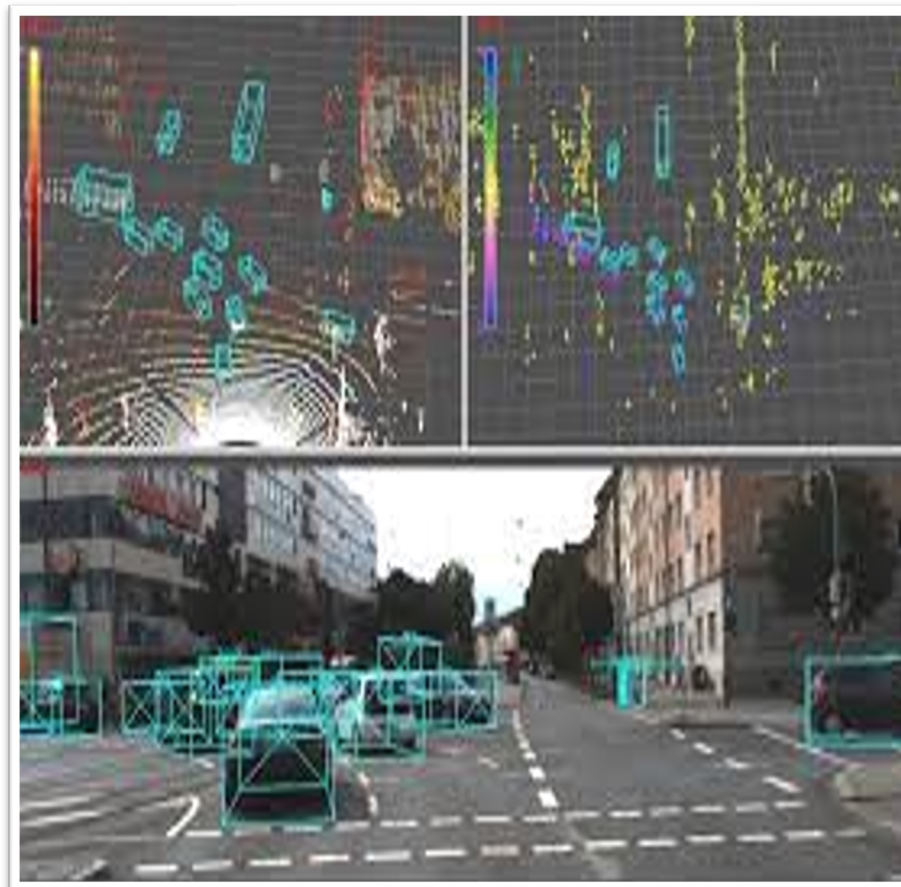
## GF's differentiated performance

**FDX<sup>®</sup>**



# How we innovate: ADAS

## End user applications



Autopilot in highway and urban traffic scenarios

## Capabilities required

-  Range
-  Field of view
-  Resolution
-  Robustness
-  Power
-  Intelligence

## GF's differentiated performance

**FDX<sup>®</sup>**

**SiGe**

**Feature-rich  
CMOS**

**FinFET**

# How we innovate: Automotive

## End user applications



**300+ mile range**

**Delivering a smartphone  
like user experience**

**Time to charge**

## Capabilities required

**Efficient power:**



**Creation**



**Conversion**



**Monitoring**

## GF's differentiated performance

**BCD**

**Feature-rich  
CMOS**

**GaN**



# Manufacturing operations leadership



**KC Ang**  
Chief Manufacturing Officer



**Peter Benyon**  
SVP and GM Malta, NY Fab



**Joseph Chia**  
VP and GM GIGA+ Singapore Fab



**Zhimin Gu**  
VP, New Singapore Fab  
Operations



**Manfred Horstmann**  
SVP and GM European Fabs



**Ken McAvey**  
VP and GM Burlington, VT Fab



**Neil Peruffo**  
VP and GM East Fishkill, NY Fab



**Pradip Singh**  
SVP & GM, Global Manufacturing  
Operations Excellence



**Yew Kong Tan**  
SVP and GM Singapore Fabs